

**Superior Thermal Barrier Coatings for
Industrial Gas-Turbine Engines Using a Novel
Solution-Precursor Plasma-Spray Process**

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SCIES Project 03- 01- SR107

DOE COOPERATIVE AGREEMENT DE-FC26-02NT41431

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Project Awarded: 07/01/03 (36 Months Duration)

\$546,000 Total Contract Value (\$546,000 DOE)

Gas-Turbine Needs and Goals

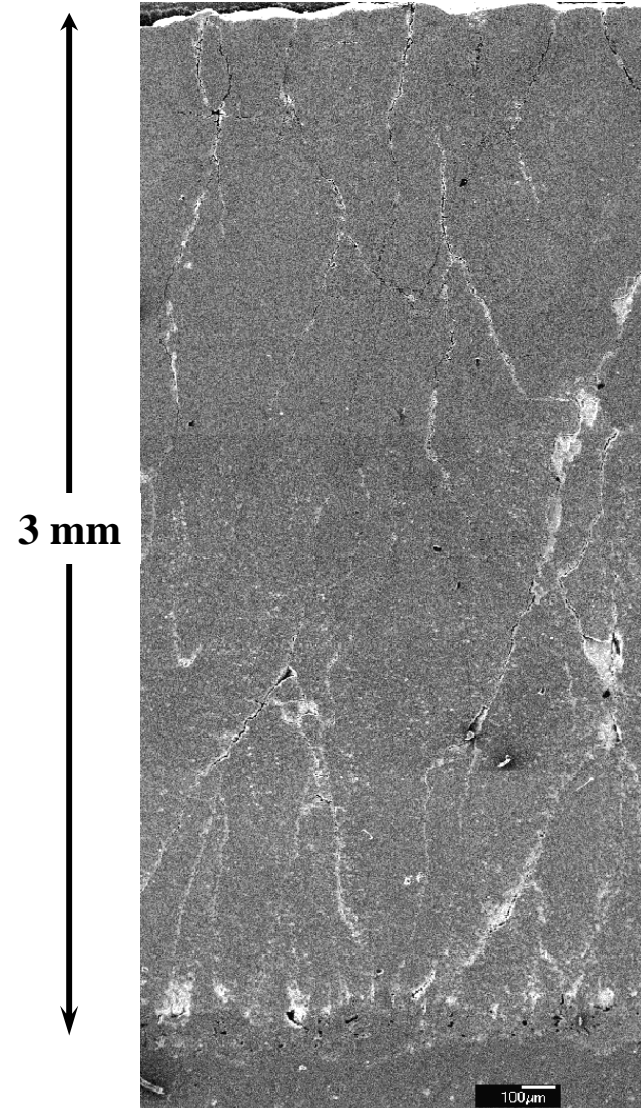
- **Highly Durable Thermal Barrier Coatings (TBCs) for Improved Performance and Efficiency, at Low Cost**
- **Ultra-Thick TBCs for Combustors, Airfoils, Blades Out-of-Airseals**
- **Four-Fold Improvement in Spallation Life Over Conventional Air Plasma Spray (APS) Ultra-Thick TBCs**
- **Transfer Technology for Producing Ultra-Thick TBCs to Industrial Partners**

Objectives and Approach

- **To Demonstrate Feasibility of Ultra-Thick (~3 mm) TBCs Using Solution-Precursor Plasma-Spray (SPPS)**
- **To Determine Mechanical Properties, Thermal Cond., Durability, and Hot-Corrosion Resistance**
- **To Elucidate Failure Mechanisms and Microstructural Thermal Stability**
- **To Identify Microstructural and Architectural Characteristics for Optimum Ultra-Thick SPPS TBCs**
- **To Obtain TBCs with Improved Durability, Thermal Resistivity and Hot-Corrosion Resistance**

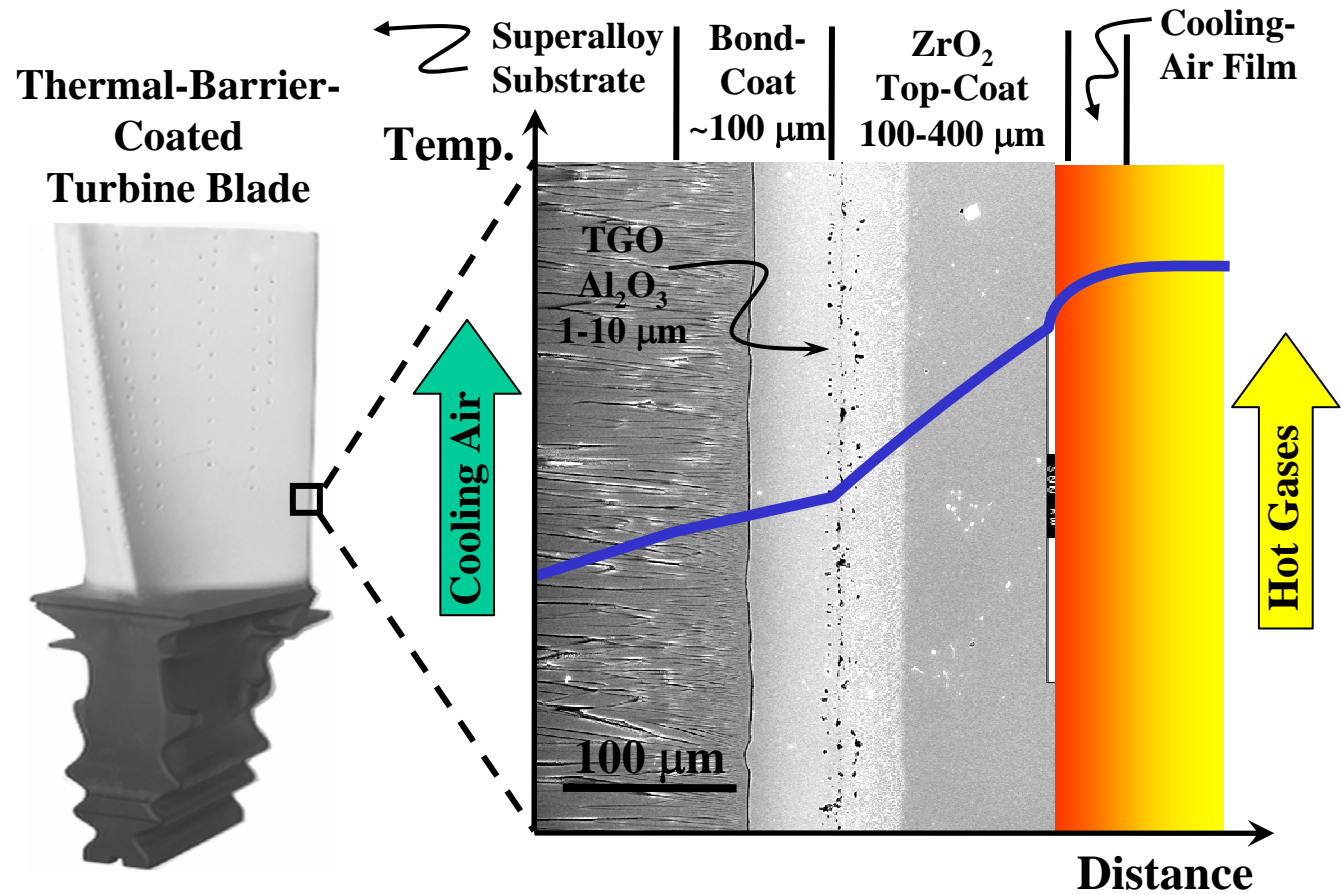
Accomplishments

- **Demonstrated the Feasibility of Depositing Ultra-Thick (~3 mm) TBCs Using the SPPS Process**
- **Determined Mechanical and Thermal Properties of SPPS Ultra-Thick TBCs**
- **Demonstrated Improved Durability in SPPS Ultra-Thick TBCs**
- **Deposited Layered TBCs for Lower Thermal Conductivities**



Thermal Barrier Coatings

- Hot-Section Metal Comp.
- Blades
- Vanes
- Combustors
- Temp. Redn. Up to 300 °C



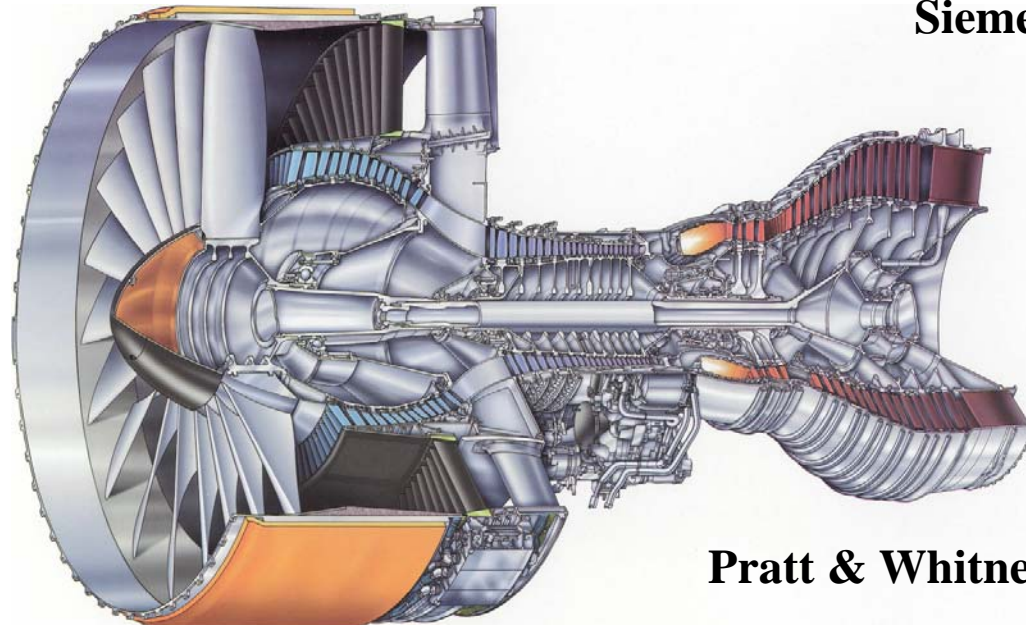
Gas-Turbine Engines

- Power Generation
- Marine Propulsion



Siemens-Westinghouse

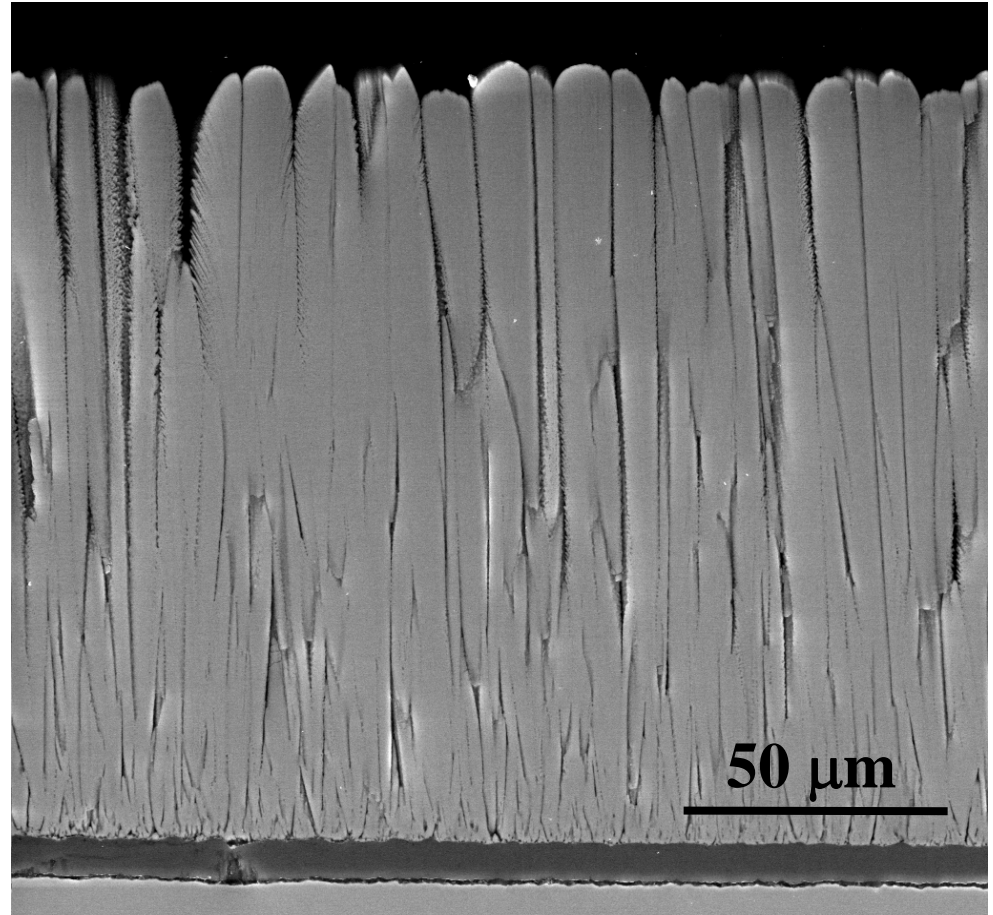
- Aircraft Propulsion



Pratt & Whitney

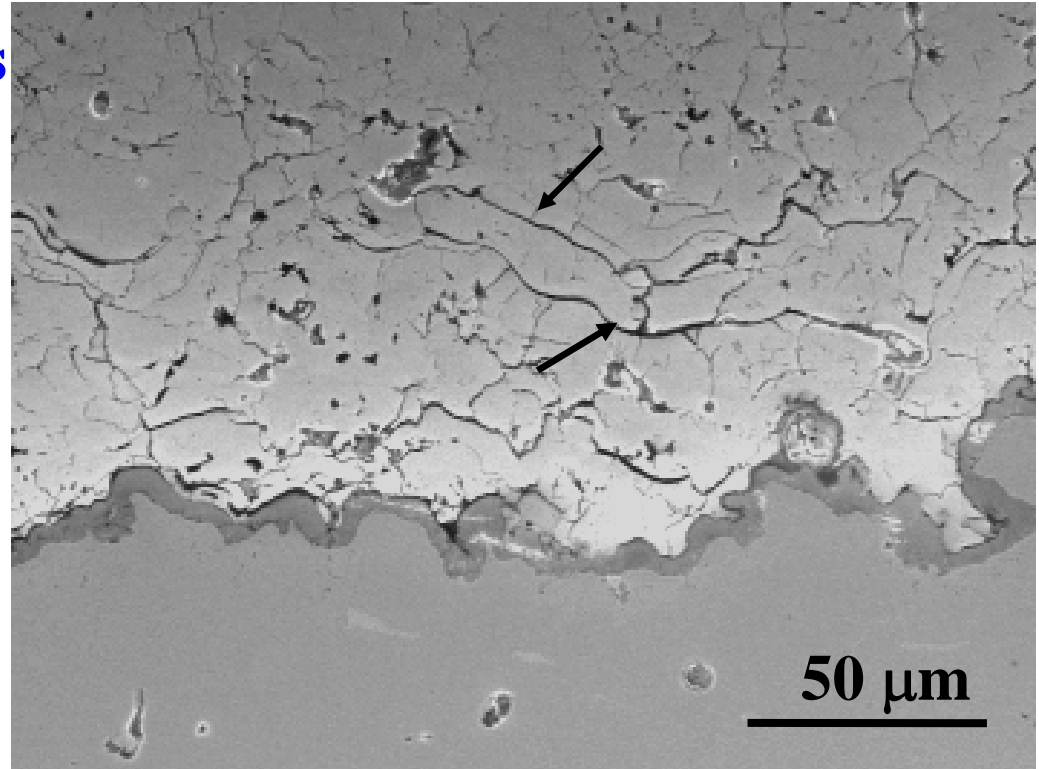
Electron-Beam PVD TBC

- Columnar Grains
- Porosity, Vertical Cracks
- Thinner (100-150 μm)
- Higher Strain Tolerance
- Higher Thermal Cond.
- Longer Spallation Life
- More Expensive
- No Hole Coverage

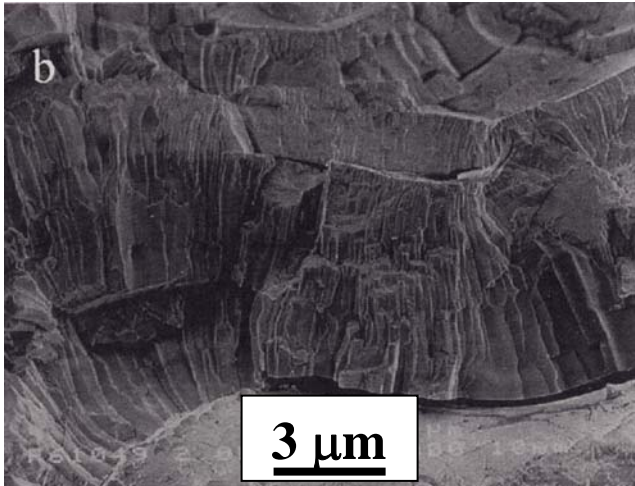
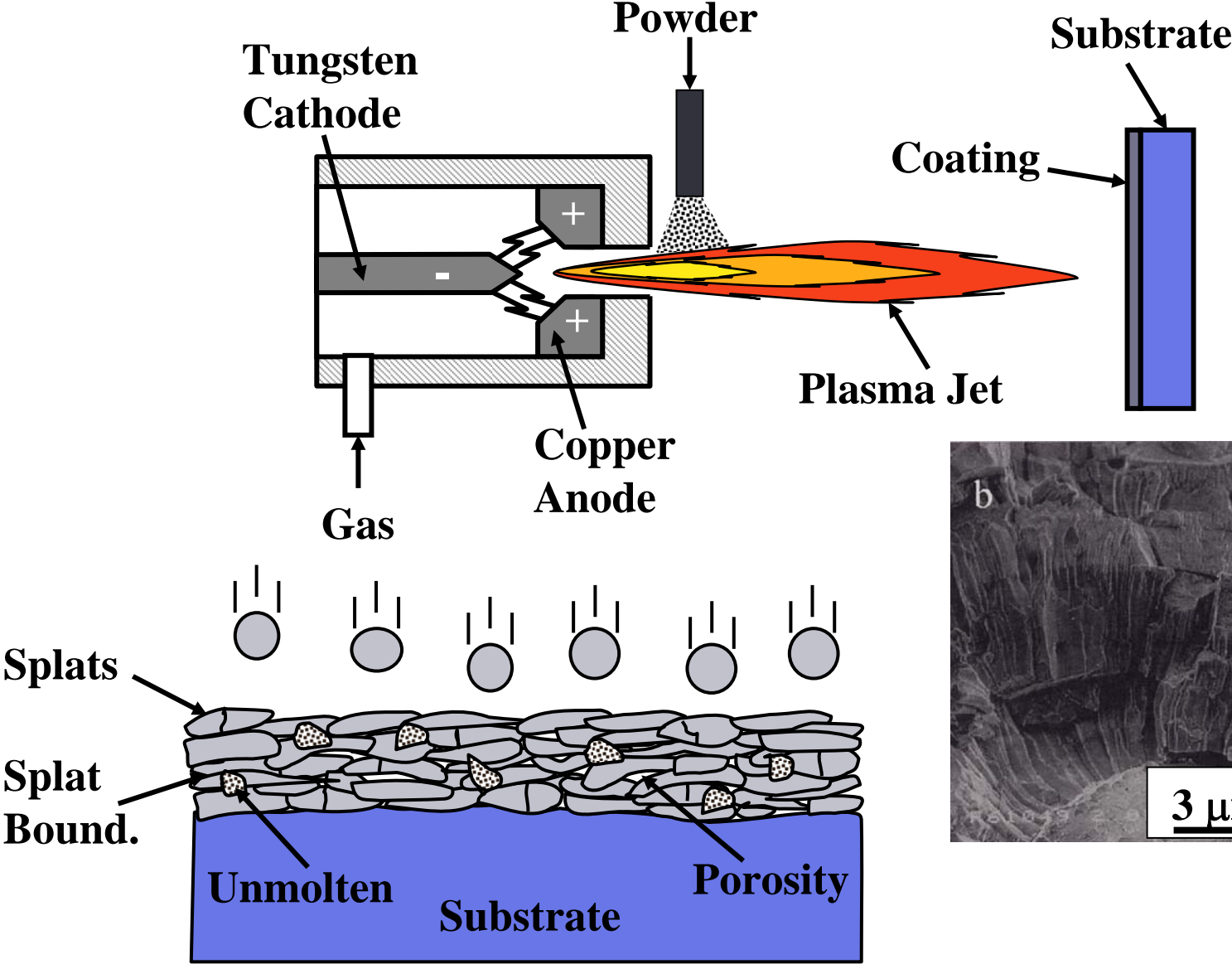


Air-Plasma Sprayed (APS) TBCs

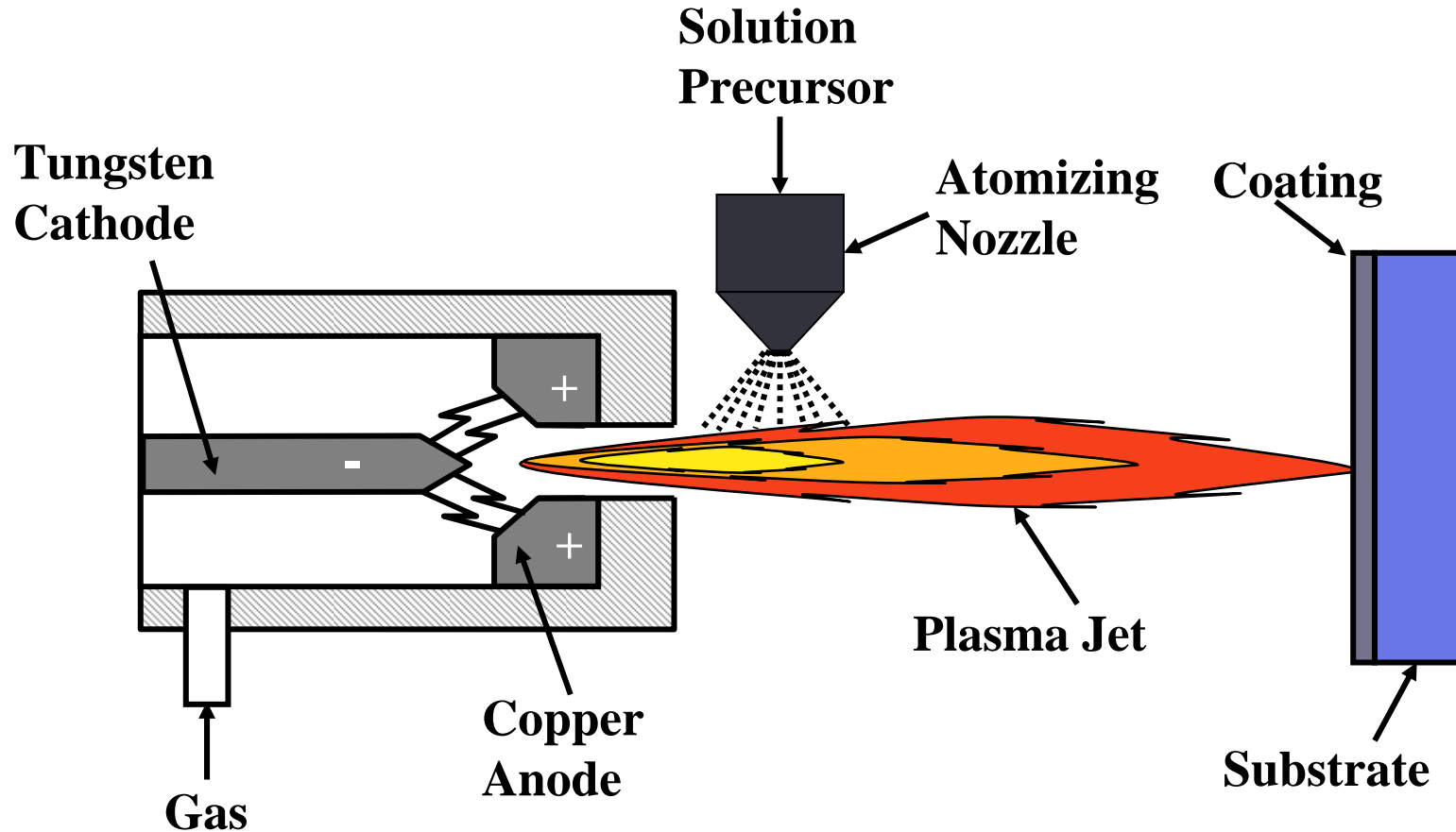
- “Splat” Grains
- Porosity, Horizontal Cracks, Splat Boundaries
- Thicker (200-400 μm)
- Rough Interface
- Lower Strain Tolerance
- Lower Thermal Cond.
- Shorter Spallation Life
- Less Expensive



Conventional Air-Plasma Spray (APS)

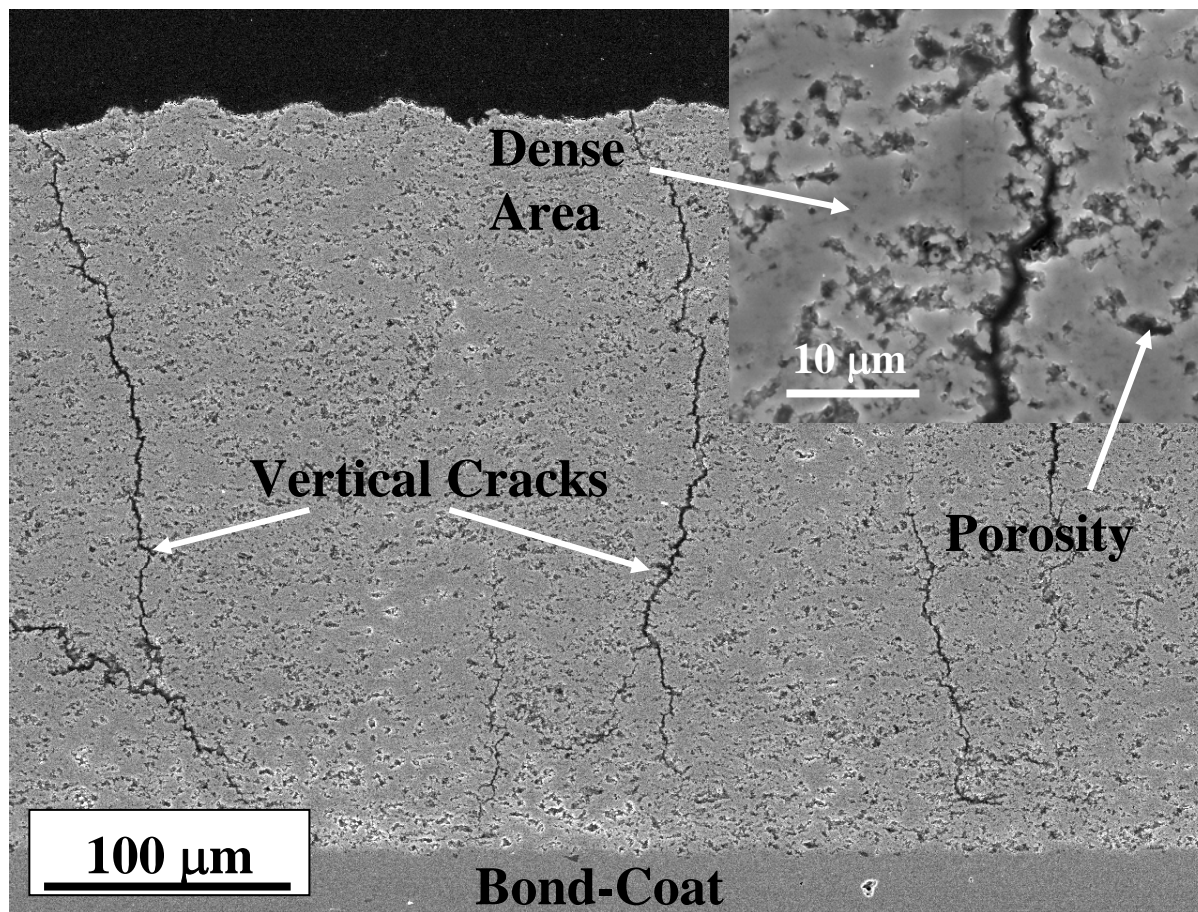


Solution-Precursor Plasma Spray (SPPS)

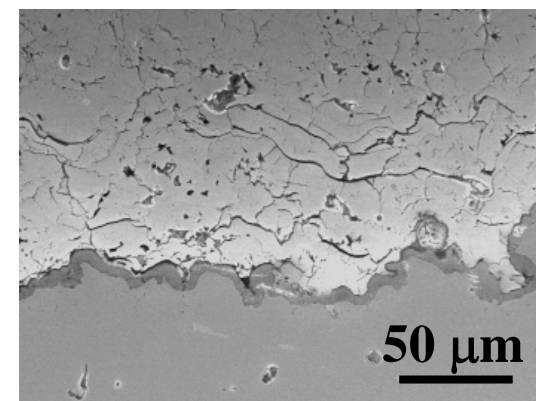
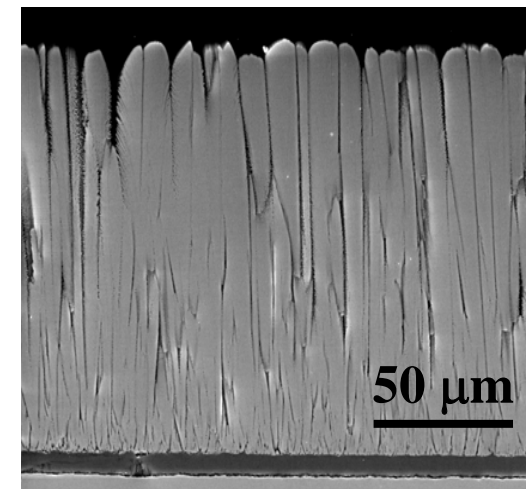


Solution Precursor: Aq Soln. Zr + Y Salts \Rightarrow 7YSZ

SPPS TBCs: ZrO_2 -7 wt% Y_2O_3



EB-PVD



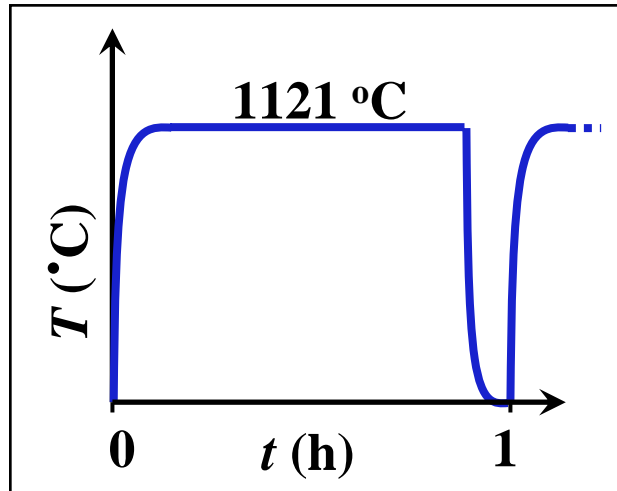
- No Macro-Splat Boundaries
- Vertical Cracking
- Porosity (18-20%)

Conv. APS

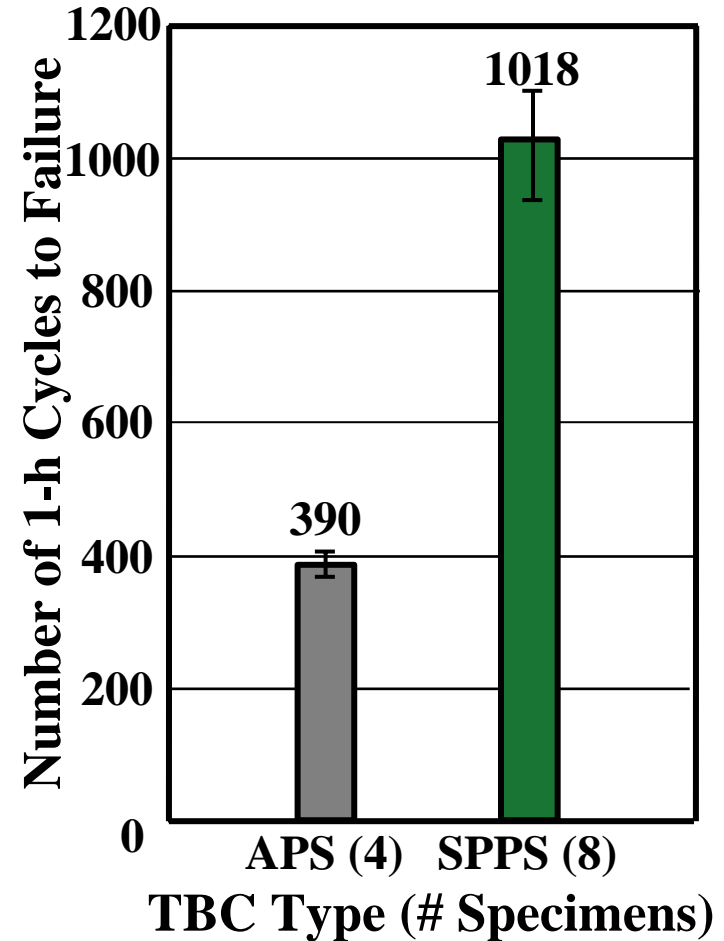
Durability of SPPS TBCs

- Same Bond-Coat for APS and SPPS
- TBC Thickness: $\sim 250 \mu\text{m}$

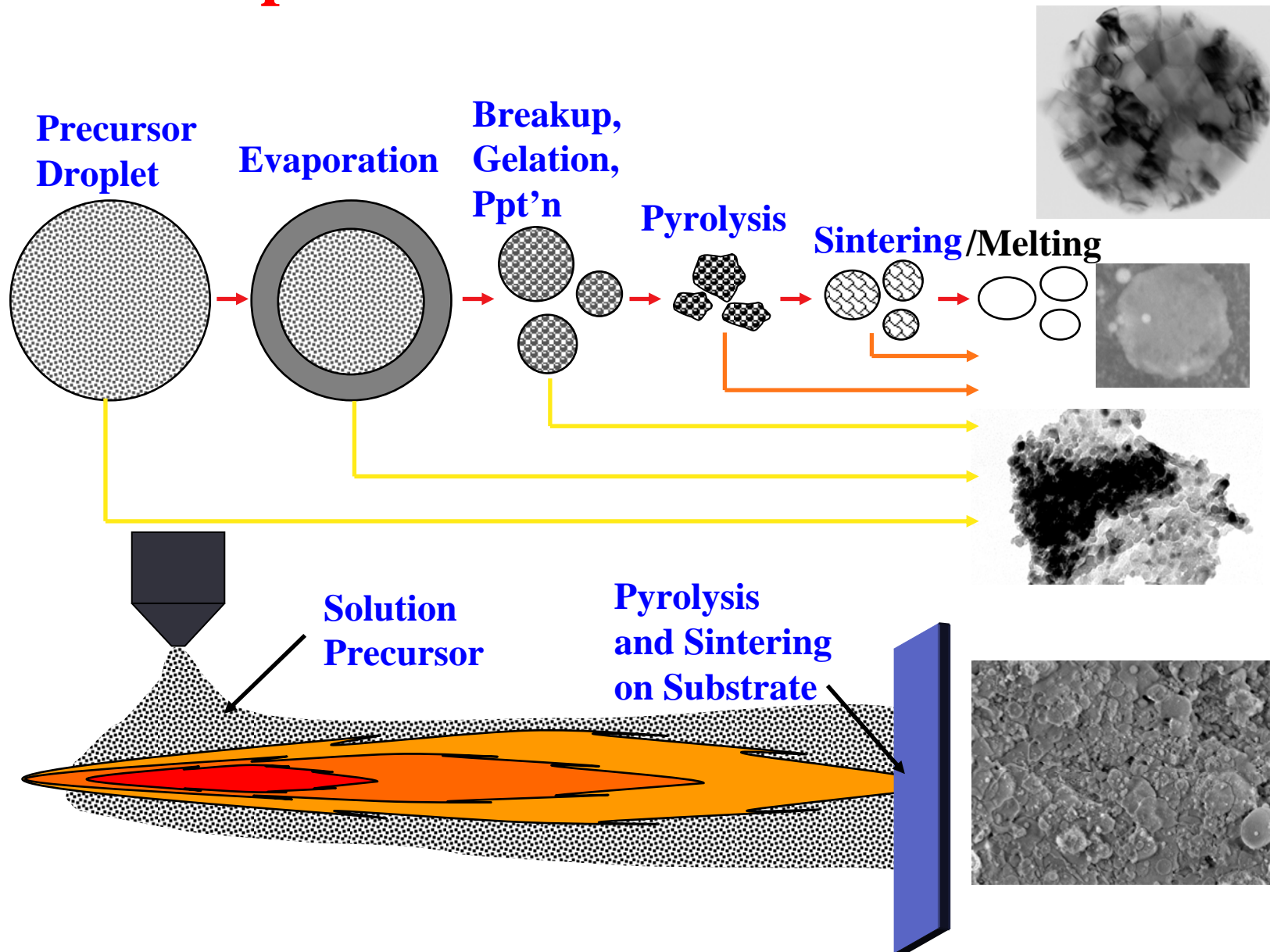
Thermal-Cycling Life Test



- No Macro-Splat Boundaries
- Vertical Cracking
- Porosity (18-20%)



SPPS Deposition Mechanisms



Ultra-Thick TBCs

**SPPS Process Uniquely
Suited for Ultra-Thick TBCs**

Advantages

- Lower Thermal Diffusivities
- Increased Engine Operating Temperatures
- Improved Efficiency
- Lower Cooling Requirements

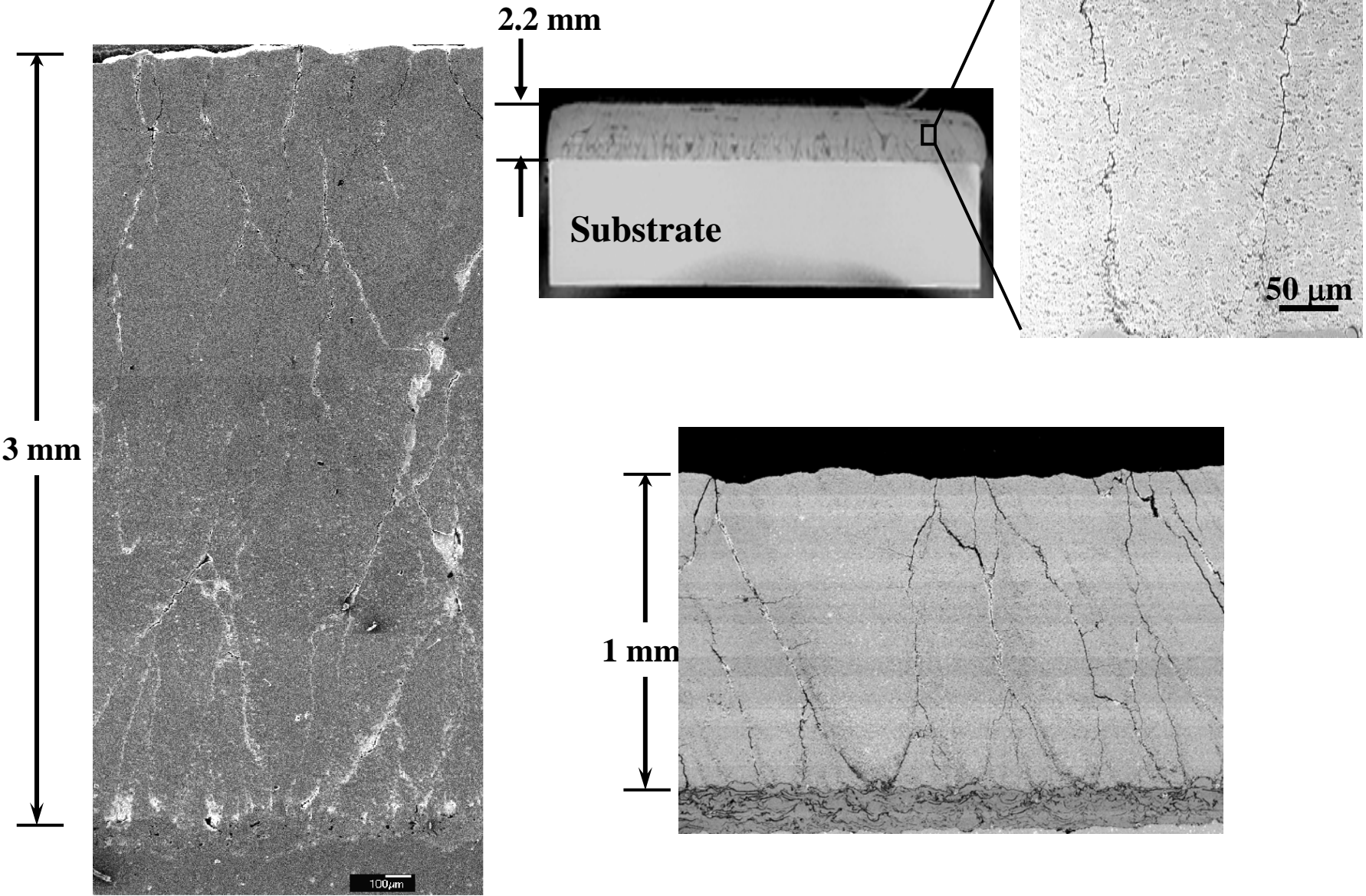
Applications

- Turbine Blades Out-of-Air-Seals
- Turbine Airfoils
- Combustors

Current Limitations

- Ultra-Thick TBCs Difficult To Deposit Using APS
- Need Graded Interfaces

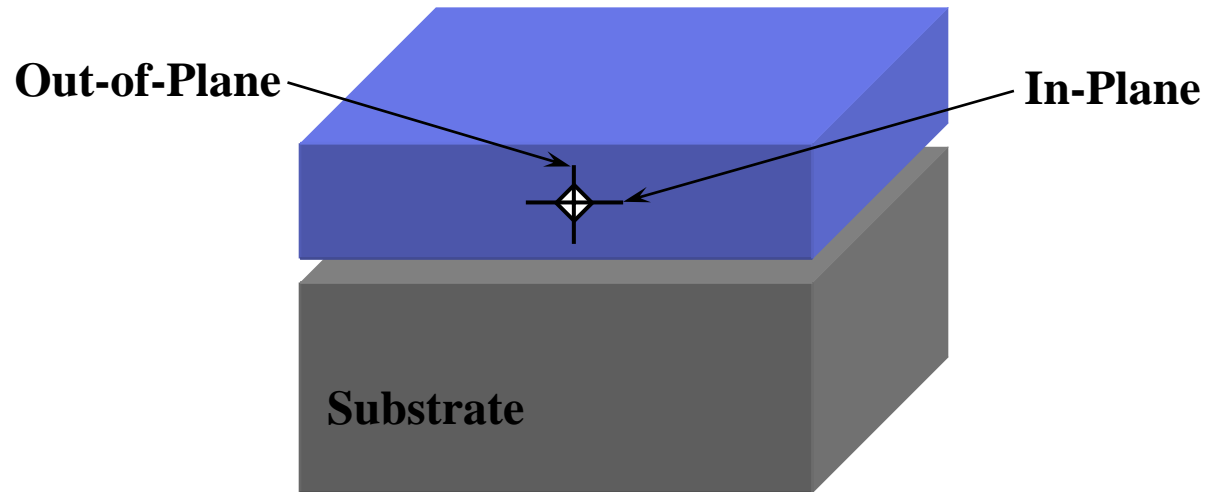
Ultra-Thick SPPS TBCs (7YSZ)



Toughness: Vickers Indentation

Free-Standing Coatings (~3 mm)

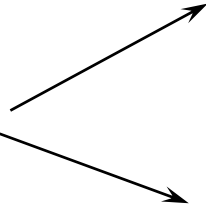
- SPPS
- Conventional APS



Vickers Indentation

SPPS

Out-of-Plane



APS

QuickTime™ and a
TIFF (LZW) decompressor
are needed to see this picture.

QuickTime™ and a
TIFF (LZW) decompressor
are needed to see this picture.

In-Plane



Toughness

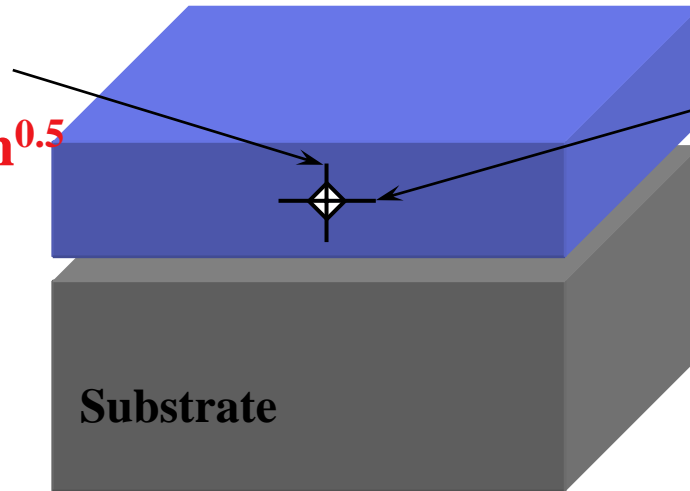
$$K_{IC} = 0.016(E/H)^{0.5}Pc^{-1.5} \text{ (Lawn et al.)}$$

($P=49$ N)
(H from Hardness Test and E from Comp. Test)

Out-of-Plane

SPPS: 1.17 MPa.m^{0.5}

APS: N/A



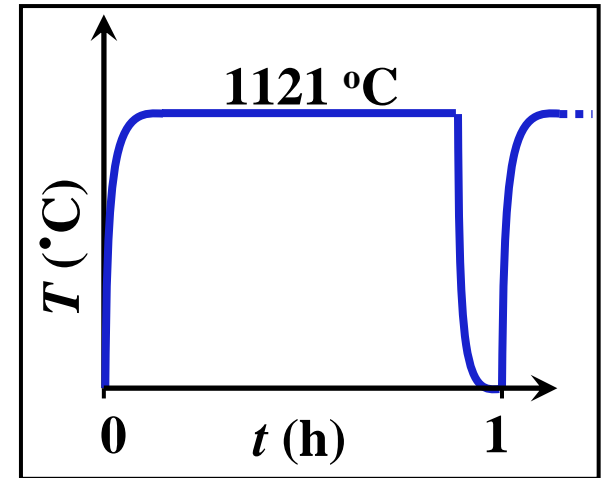
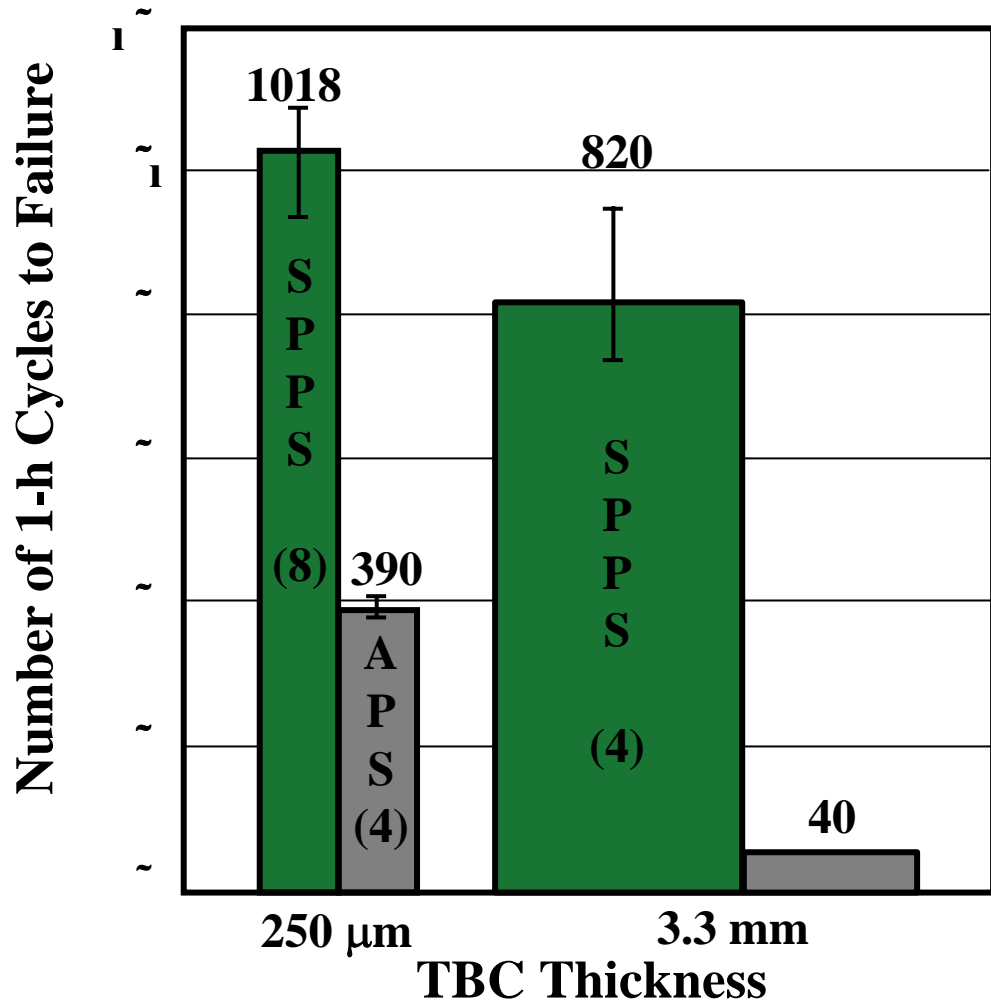
In-Plane

SPPS: 1.72 MPa.m^{0.5}

APS: 0.26 MPa.m^{0.5}

**SPPS TBCs 6 Times Tougher
in the Important In-Plane Direction:
Lack of Macro-Splat Boundaries**

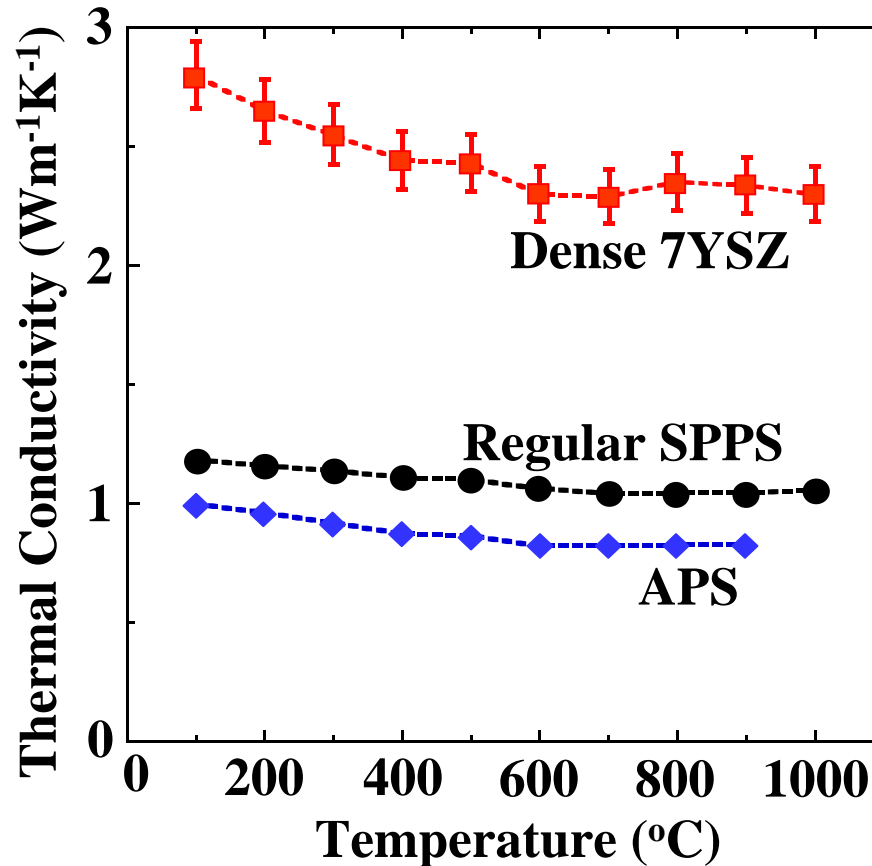
Thermo-Mechanical Durability



- Vertical Cracks: Strain Tolerance
- Lack of Macro-Splat Boundaries: In-Plane Toughness

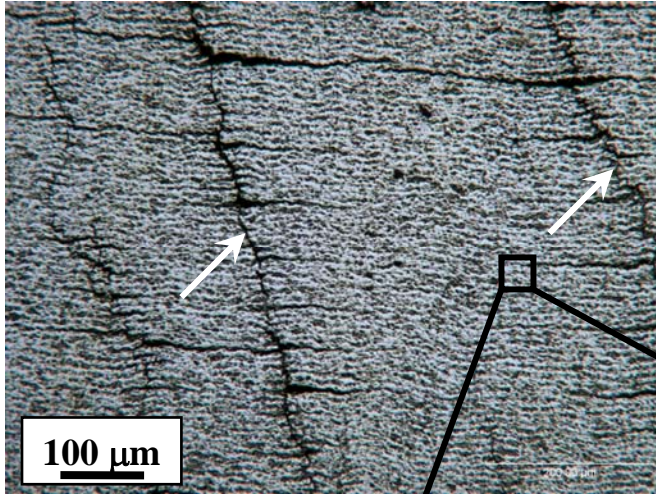
Thermal Conductivity

- Free-Standing Coatings (~1 mm)
- Laser-Flash Method



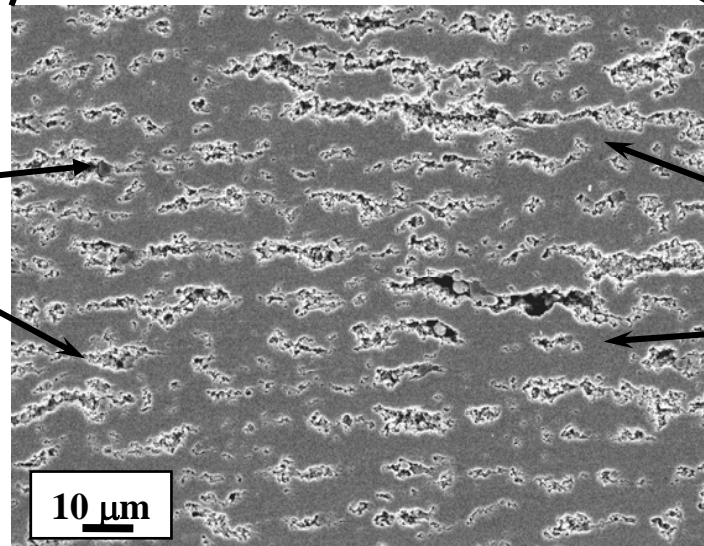
- SPPS Conductivity Higher Than APS
- Lack of Macro-Splat Boundaries

Engineering of SPPS Coating Microstructures: Layered SPPS



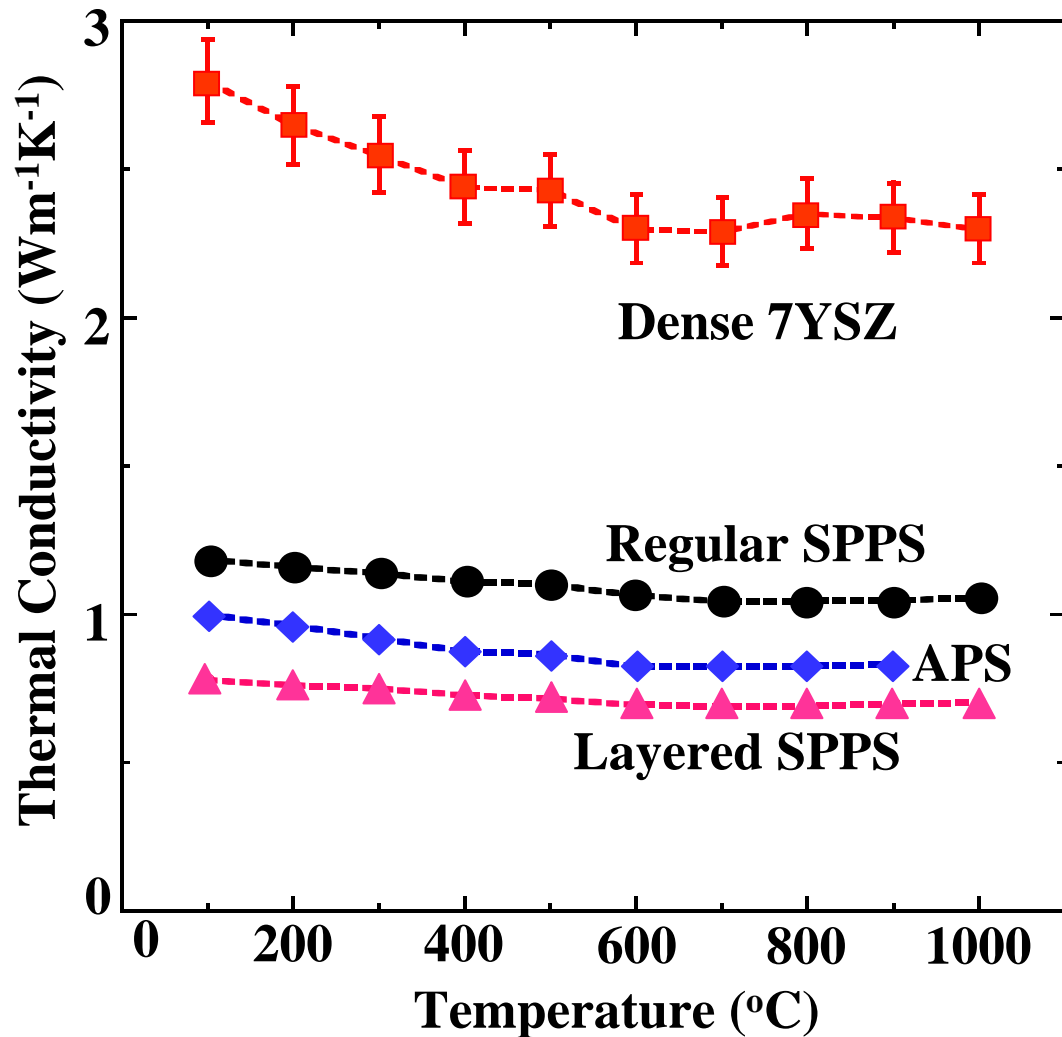
- SPPS Process Modification
- Alternating Layers of Low and High Porosity

**Porous Boundary
Region**



**Denser
Regions**

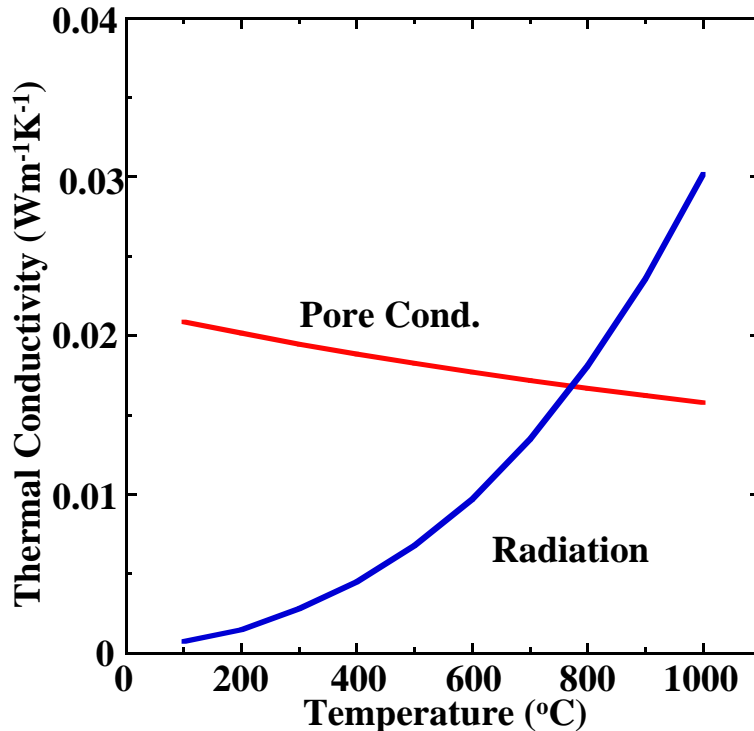
Thermal Conductivity



- Layered-SPPS Conductivity Lower than SPPS and APS
- Elongated Pores in High Porosity Layers

Thermal Conductivity Modeling: Guidelines for Microstructural Tailoring

- Analytical Modeling
- Assumptions
 - * Ignore Cond. of Pores
 - * Ignore Radiation



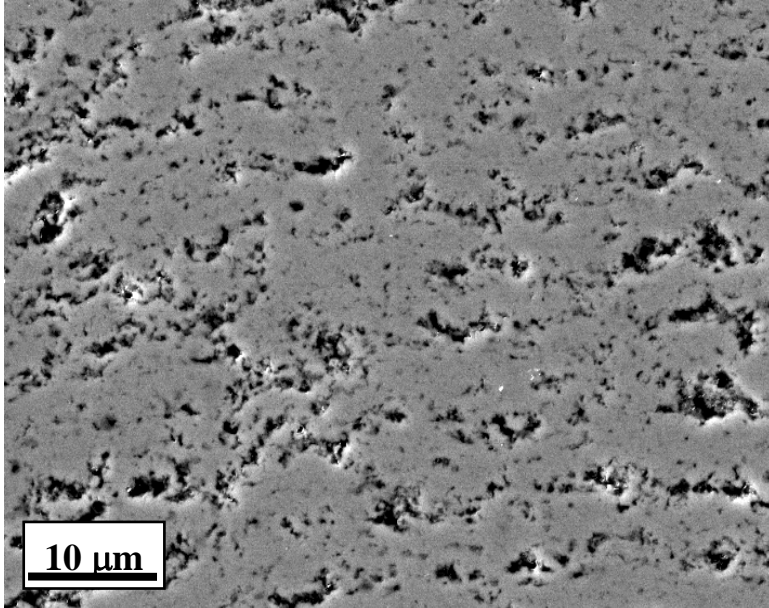
Conductivity of Gas Phase Confined in a Pore

$$k_g = \frac{k_g^0}{1 + BT / (d_t P)} \quad k_g^0 \sim 0.0241$$
$$d_t = 0.6 \mu\text{m}$$

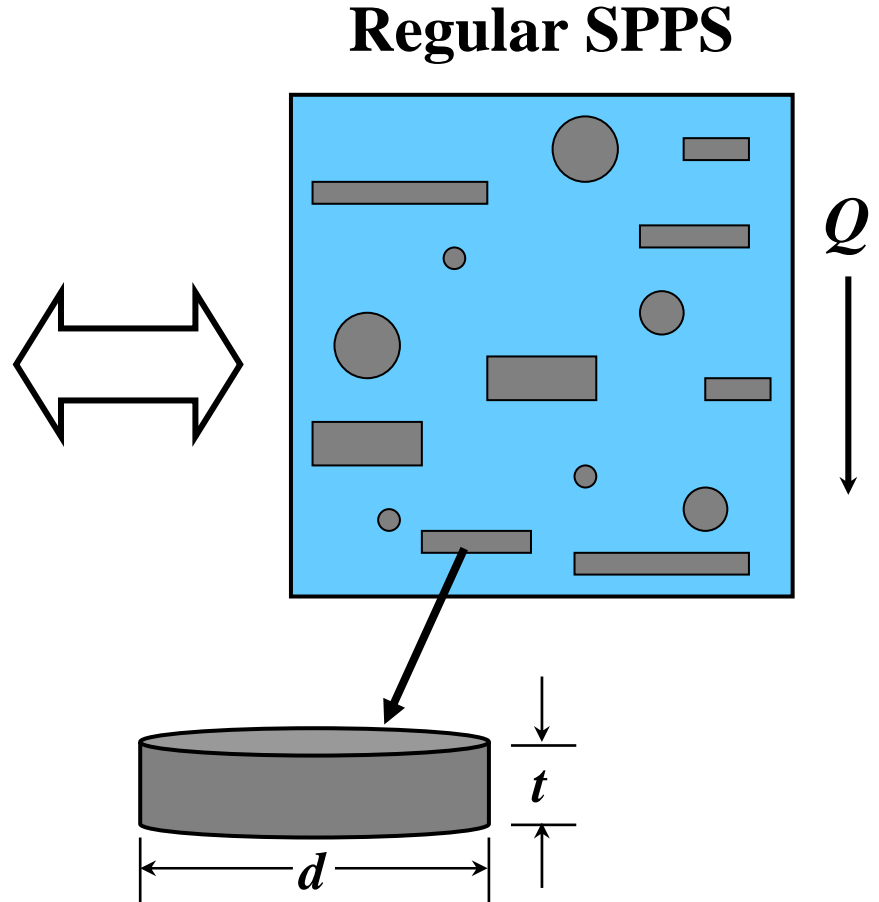
Radiation

$$k_{rad} \approx \frac{16n^2}{3\alpha} \sigma_{SB} T^3 \quad n=2.2$$
$$\alpha = 10^7 \text{ m}^{-1}$$

Thermal Conductivity Modeling: Analytical, Regular SPSS



- Mixture of Disk-Shaped and Spherical Pores
- Total Porosity ~22%



Thermal Conductivity Modeling: Analytical, Regular SPPS

Image Analysis

- Pore Vol. Fraction, Disk-Shaped Pores (ϕ_{Disk}) 0.17
- Pore Vol. Fraction, Spherical Pores (ϕ_{Sphere}) 0.07
- Aspect Ratio of Disk-Shaped Pores (d/t) 2.84
- Measured Density (Archimedes Principle) 4.73 Mg/m³
- Av. Orientation of Disk-Shaped Pores 88°

Thermal Conductivity Modeling: Analytical, Regular SPPS

Non-interacting Spherical Pores

$$\frac{k_{SphericalPores}}{k_{Dense}} = 1 - \frac{3}{2} \phi_{Sphere}$$

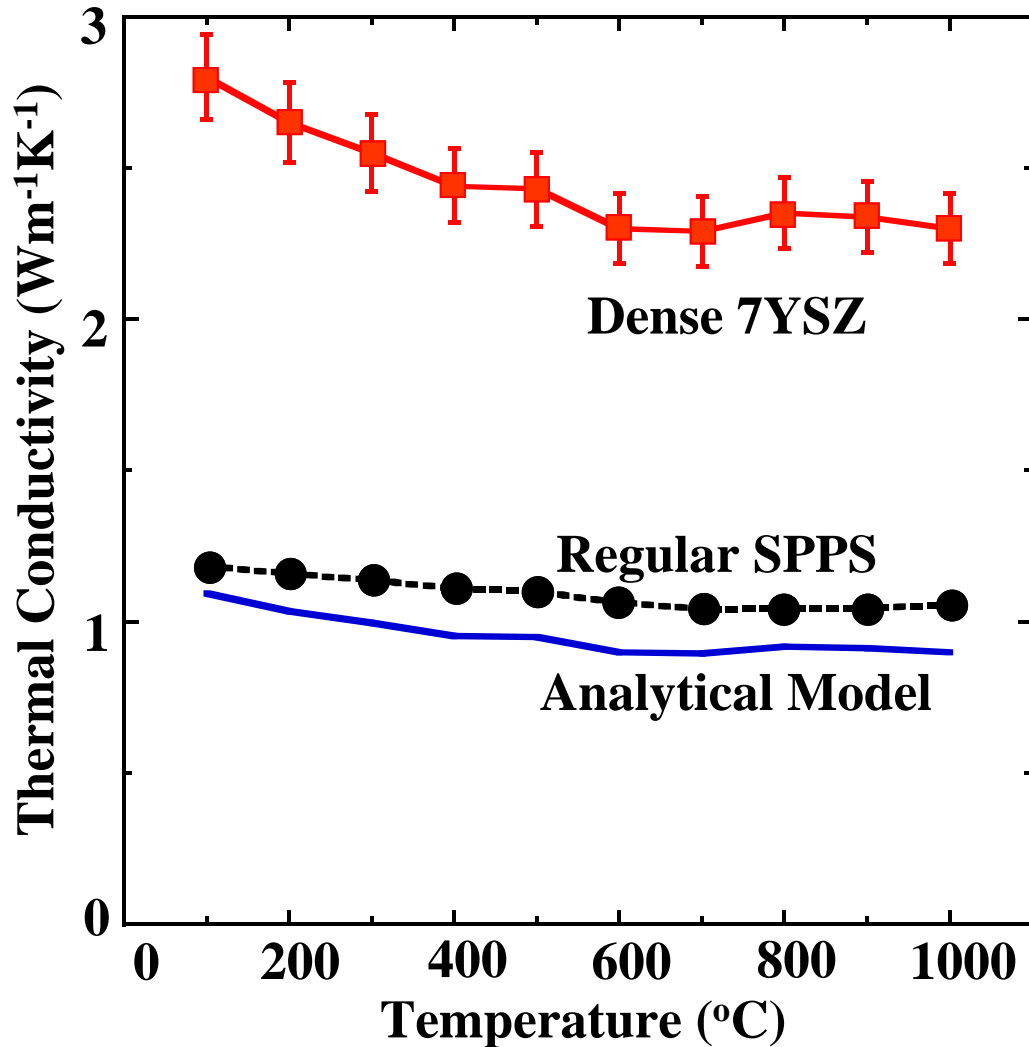
Aligned Disk-Shaped Pores

$$\frac{k_{DiskPores}}{k_{Dense}} = 1 - \left(\frac{2\phi_{Disk}}{\pi} \right) \left(\frac{d}{t} \right)$$

Effective Thermal Conductivity of Mixture

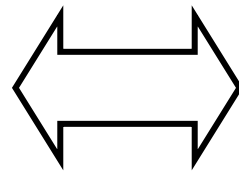
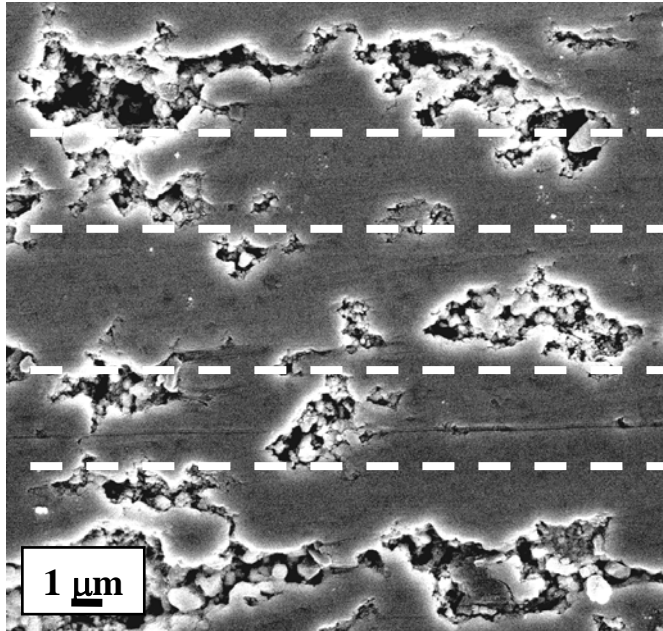
$$k_{SPPS} = \frac{1}{2} \left\{ f_2 \left(\frac{\phi_{Disk}}{1 - \phi_{Sphere}} \right) f_1 \left(\phi_{Sphere} \right) + f_1 \left(\frac{\phi_{Sphere}}{1 - \phi_{Disk}} \right) f_2 \left(\phi_{Disk} \right) \right\} k_{Dense}$$

Thermal Conductivity Modeling: Analytical, Regular SPPS

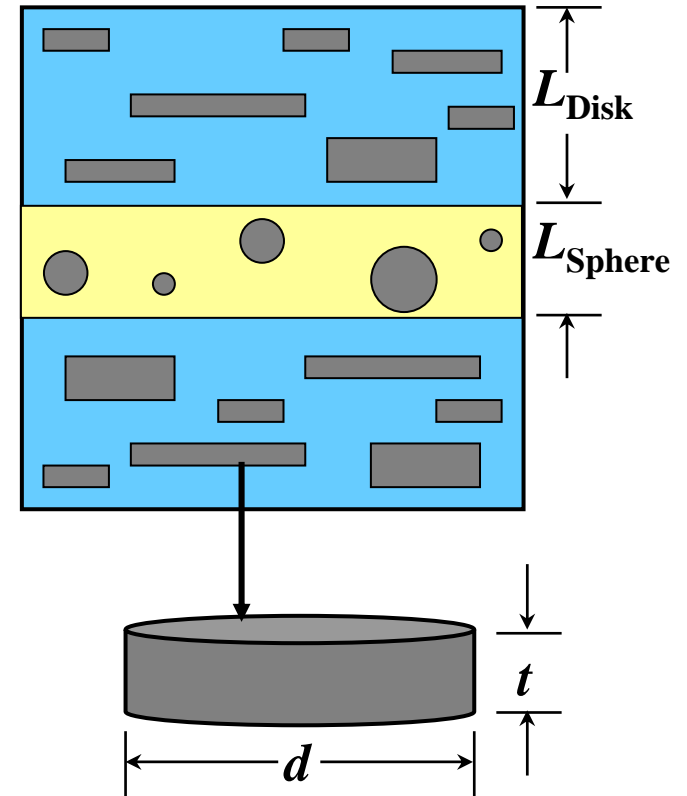


- Calculated Th. Cond. within 13% of Expt.
- No Adjustable Param.
- Idealized Micro-structures

Thermal Conductivity Modeling: Analytical, Layered SPSS



Q



- **Alternate Layers of:**
 - * **Low, Spherical Porosity**
 - * **High, Disk-Shaped Porosity**
- **Total Porosity $\sim 33\%$**

Thermal Conductivity Modeling: Analytical, Layered SPPS

Image Analysis

- Pore Vol. Fraction, Disk-Shaped Pores (ϕ_{Disk}) 0.24
- Pore Vol. Fraction, Spherical Pores (ϕ_{Sphere}) 0.06
- Aspect Ratio of Disk-Shaped Pores (d/t) 3.34
- Av. Thickness of High-Porosity Layer (L_{Disk}) 6 μm
- Av. Thickness of Low-Porosity Layer (L_{Sphere}) 4 μm
- Measured Density (Archimedes Principle) 4.13 Mg/m^3
- Av. Orientation of Disk-Shaped Pores 89°

Thermal Conductivity Modeling: Analytical, Layered SPSS

Non-interacting Spherical Pores

$$\frac{k_{SphericalPores}}{k_{Dense}} = 1 - \frac{3}{2} \phi_{Sphere}$$

Aligned Disk-Shaped Pores

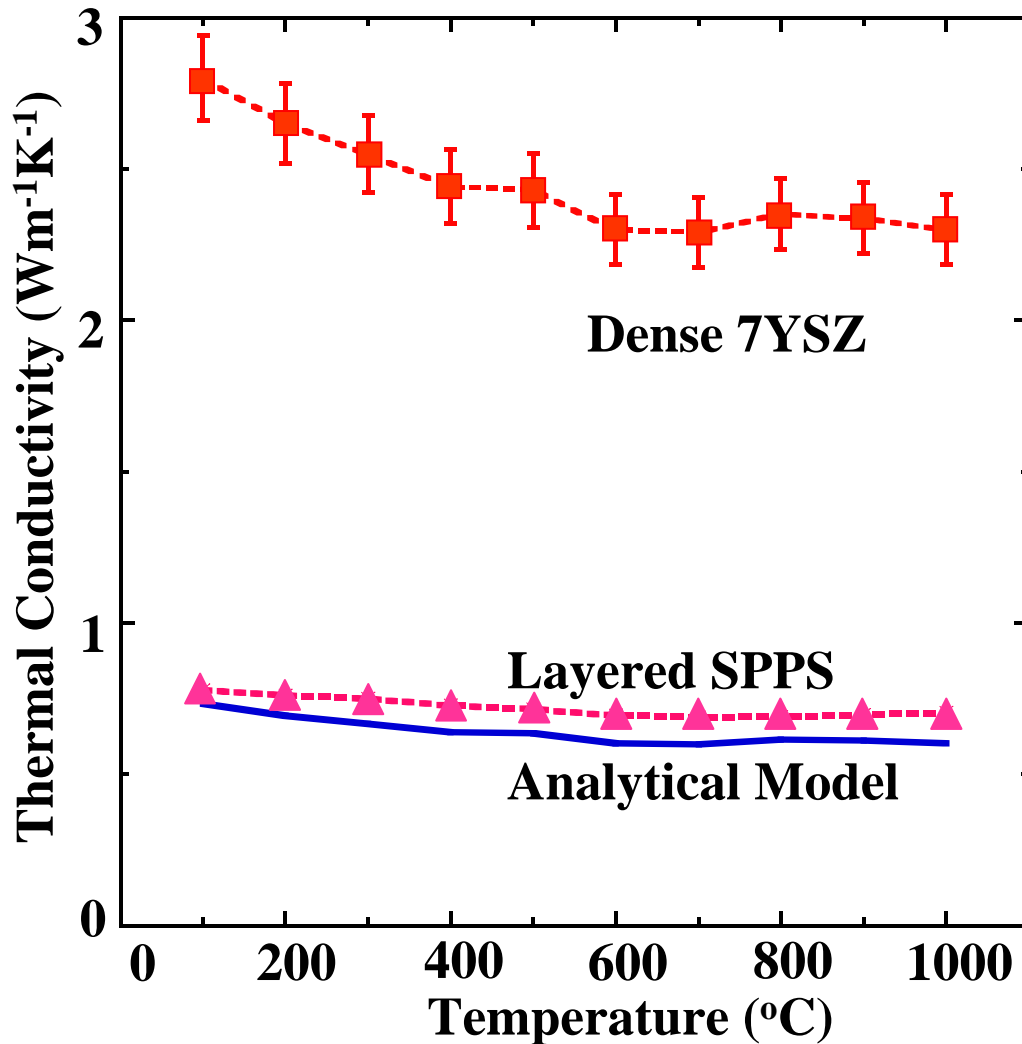
$$\frac{k_{DiskPores}}{k_{Dense}} = 1 - \left(\frac{2\phi_{Disk}}{\pi} \right) \left(\frac{d}{t} \right)$$

Effective Thermal Conductivity of Layered Composite

$$k_{LayeredSPSS} = \left(\frac{f_1(\phi_{Sphere}) f_2(\phi_{Disk}) (L_{Sphere} + L_{Disk})}{f_1(\phi_{Sphere}) L_{Disk} + f_2(\phi_{Disk}) L_{Sphere}} \right) k_{Dense}$$

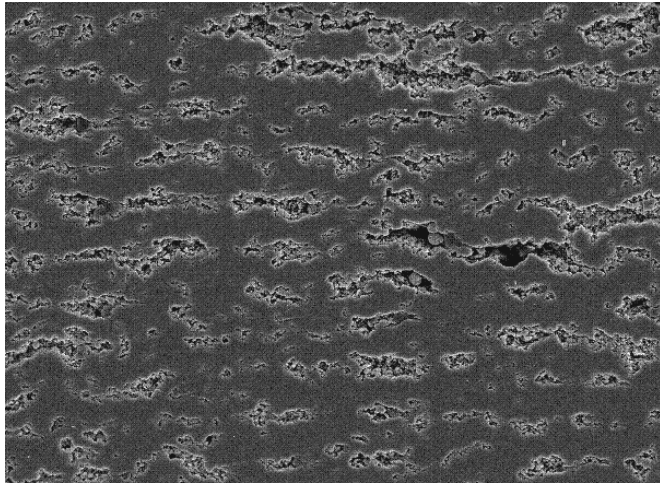
Shafiro et al., 2000; Lu et al., 2001

Thermal Conductivity Modeling: Analytical, Layered SPSS

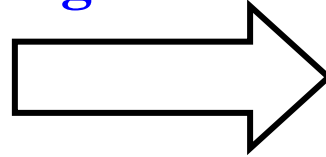


- Calculated Th. Cond. within 11% of Expt.
- No Adjustable Param.
- Idealized Micro-structures

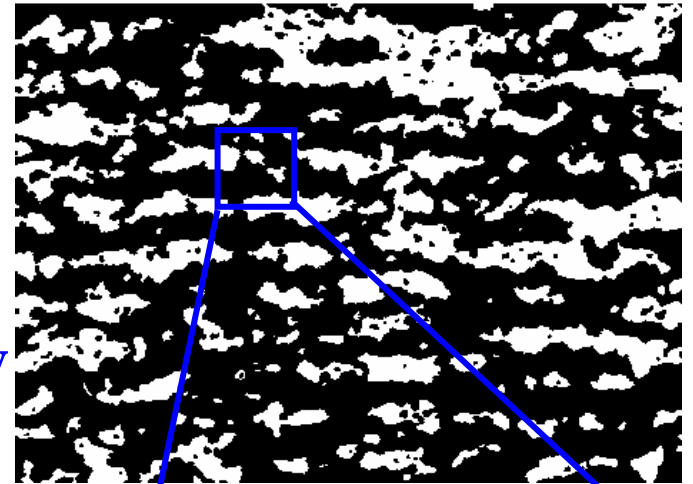
Thermal Conductivity Modeling: OOF (2-D)



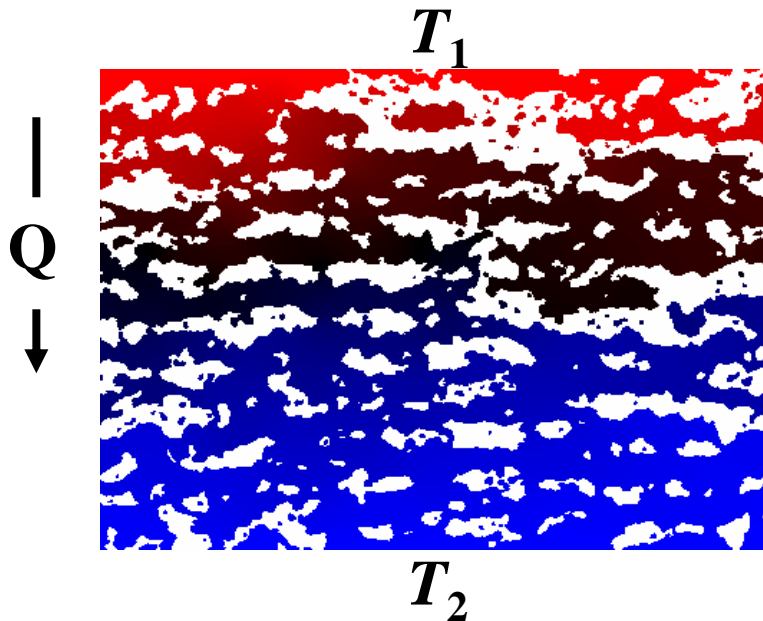
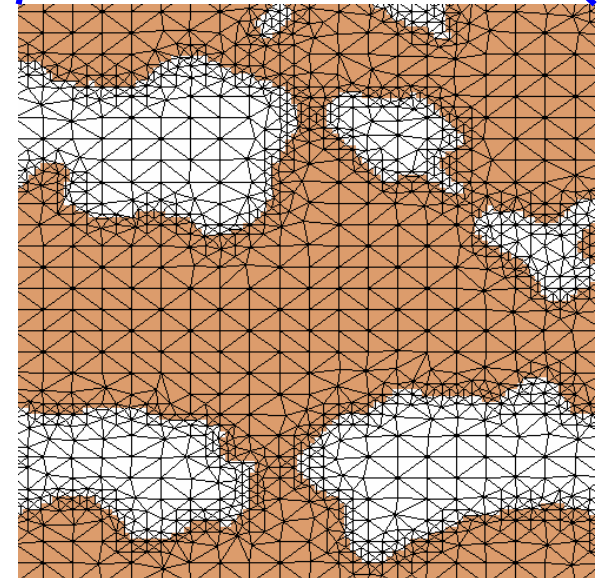
SEM
Image



Binary
Image

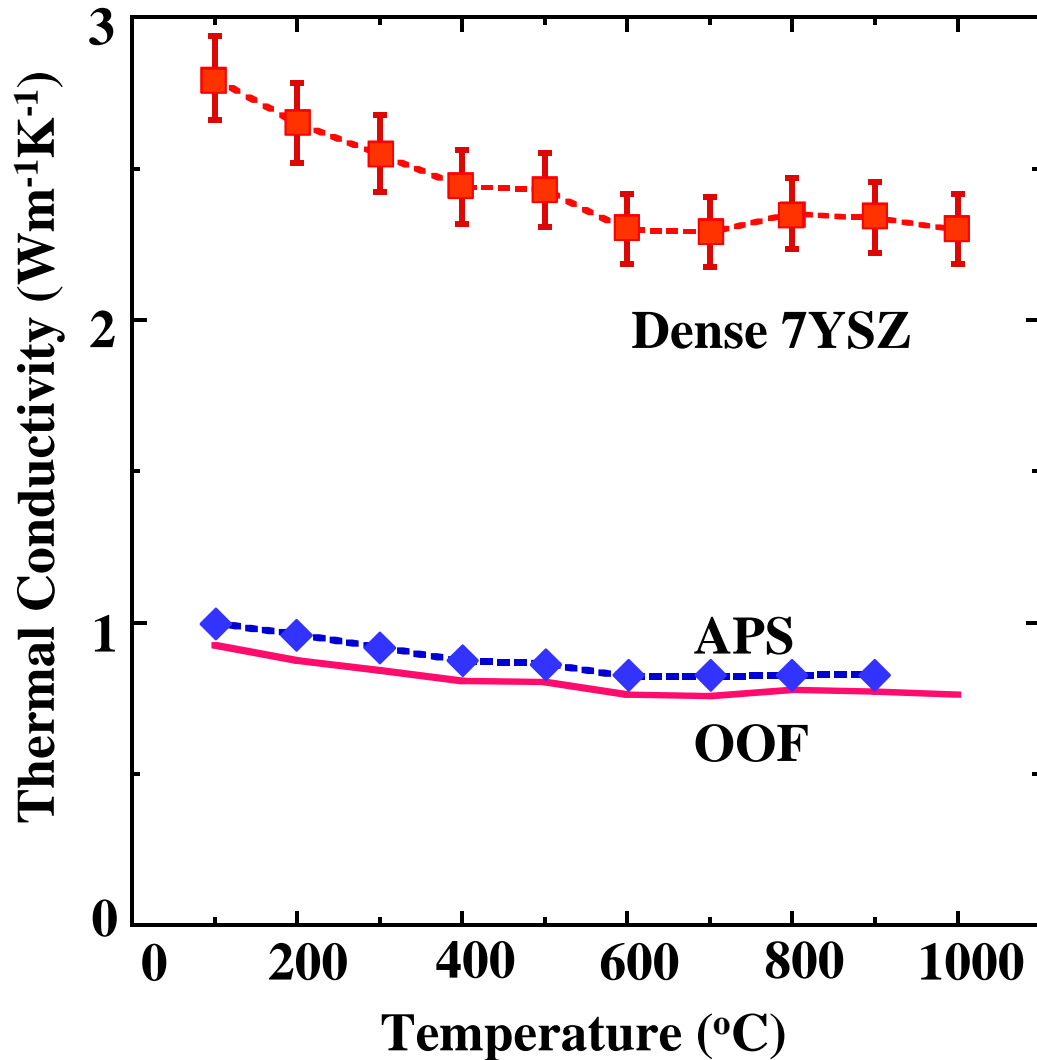


Meshing



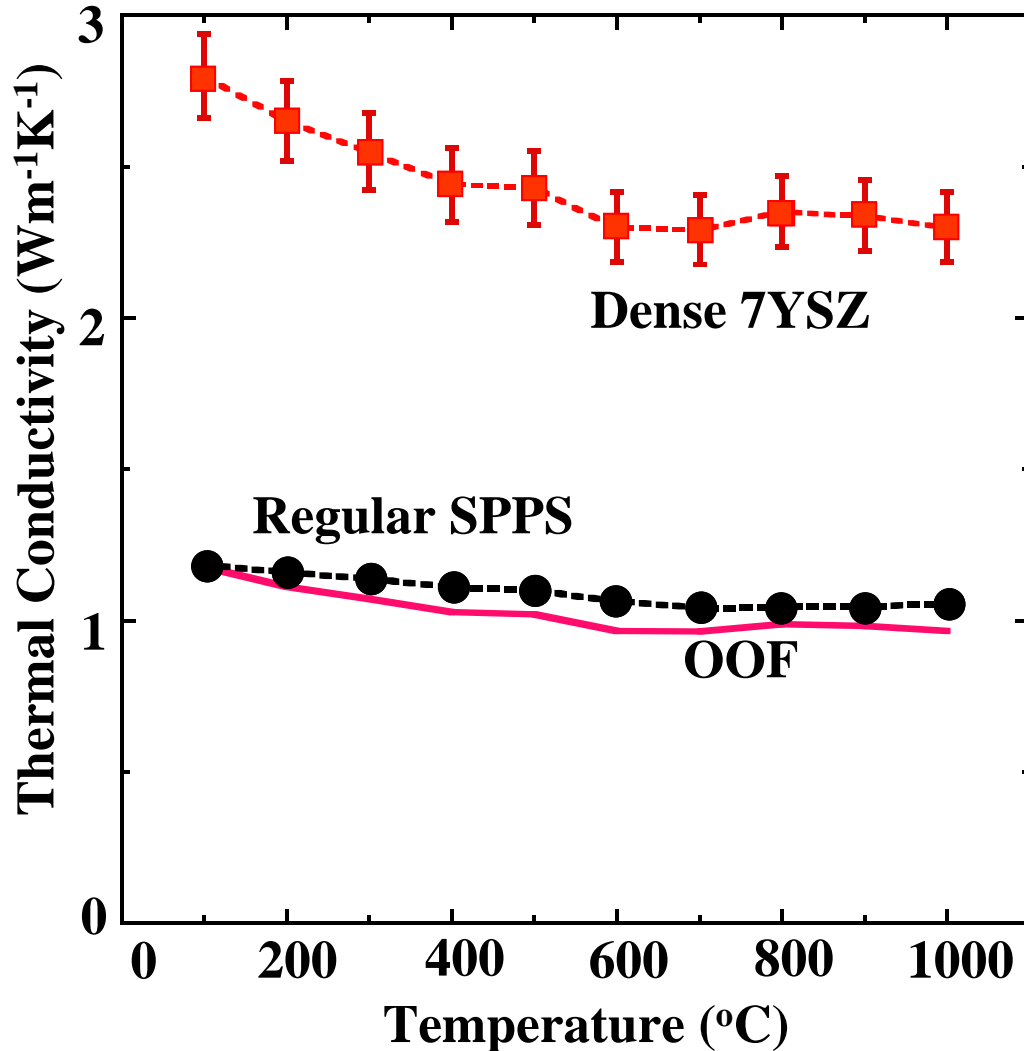
←
Equilibrate

Thermal Conductivity Modeling: OOF, APS



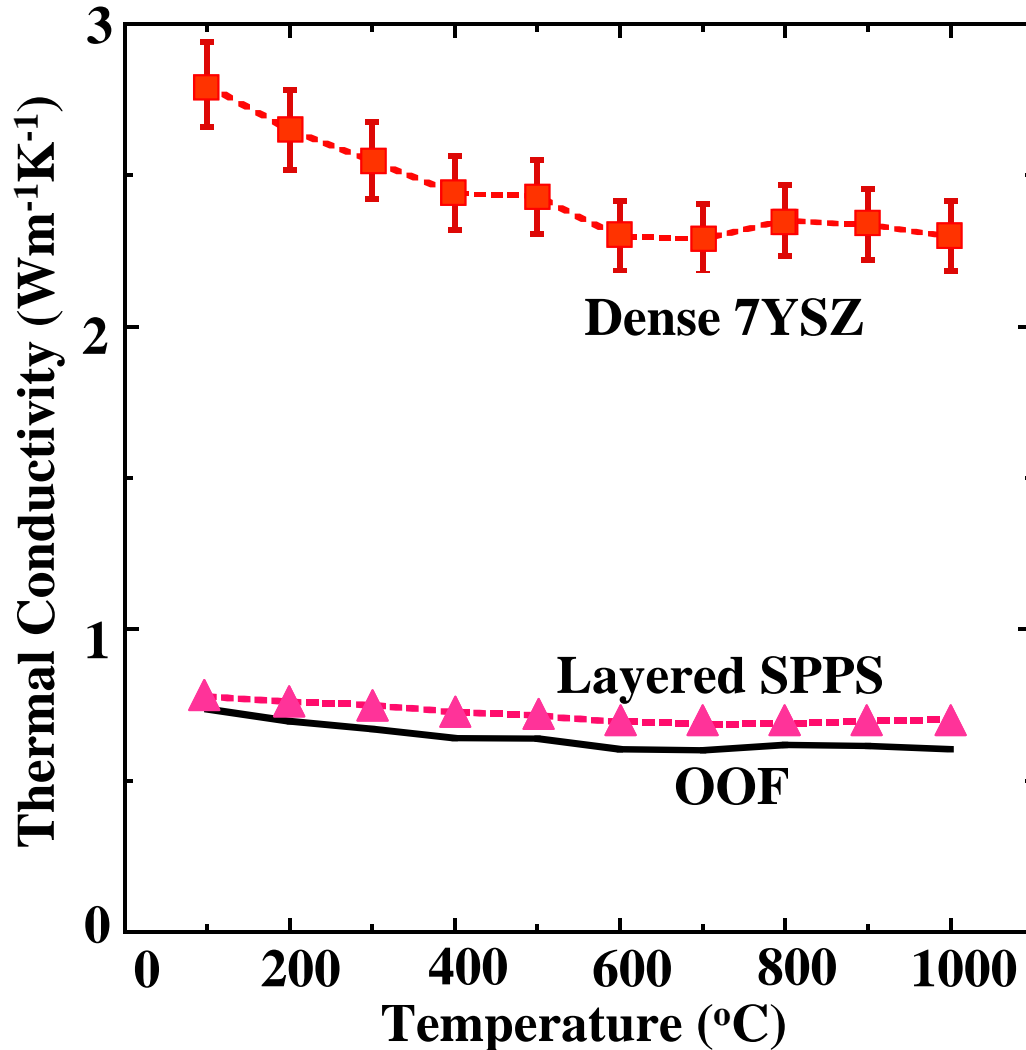
• Calculated Th. Cond.
within 7% of Expt.

Thermal Conductivity Modeling: OOF, Regular SPPS



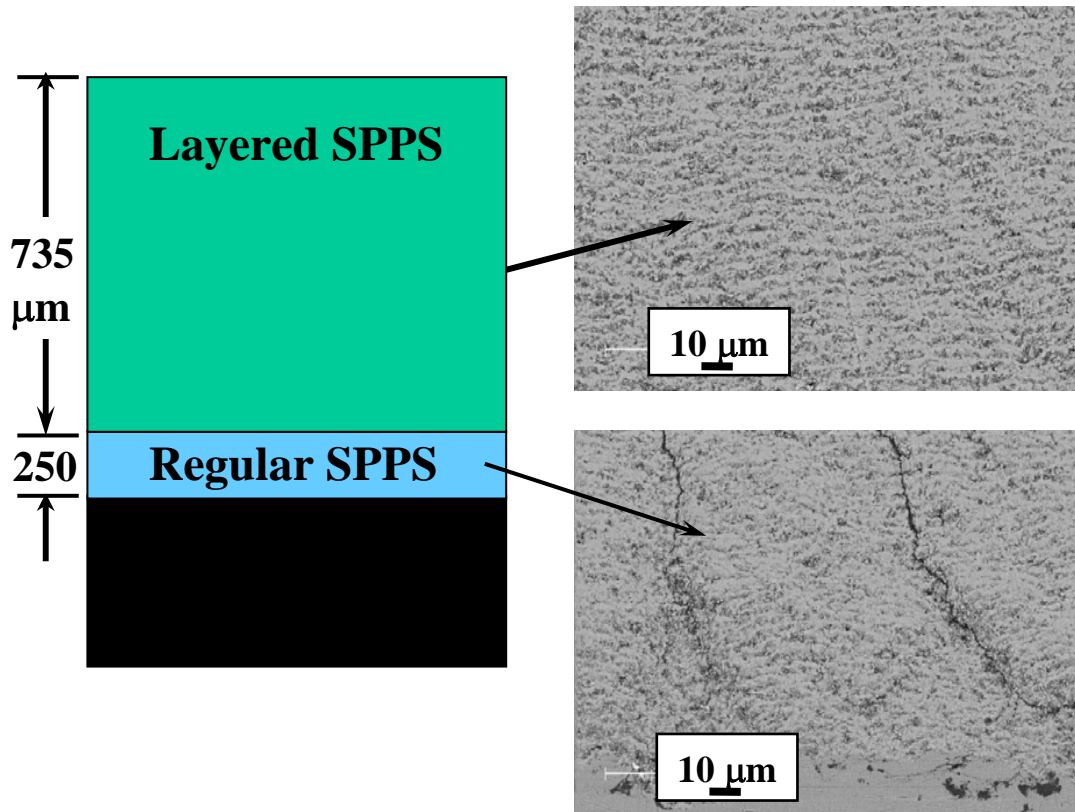
- Calculated Th. Cond. within 6% of Expt.
- Better Than Analytical Model

Thermal Conductivity Modeling: OOF, Layered SPPS

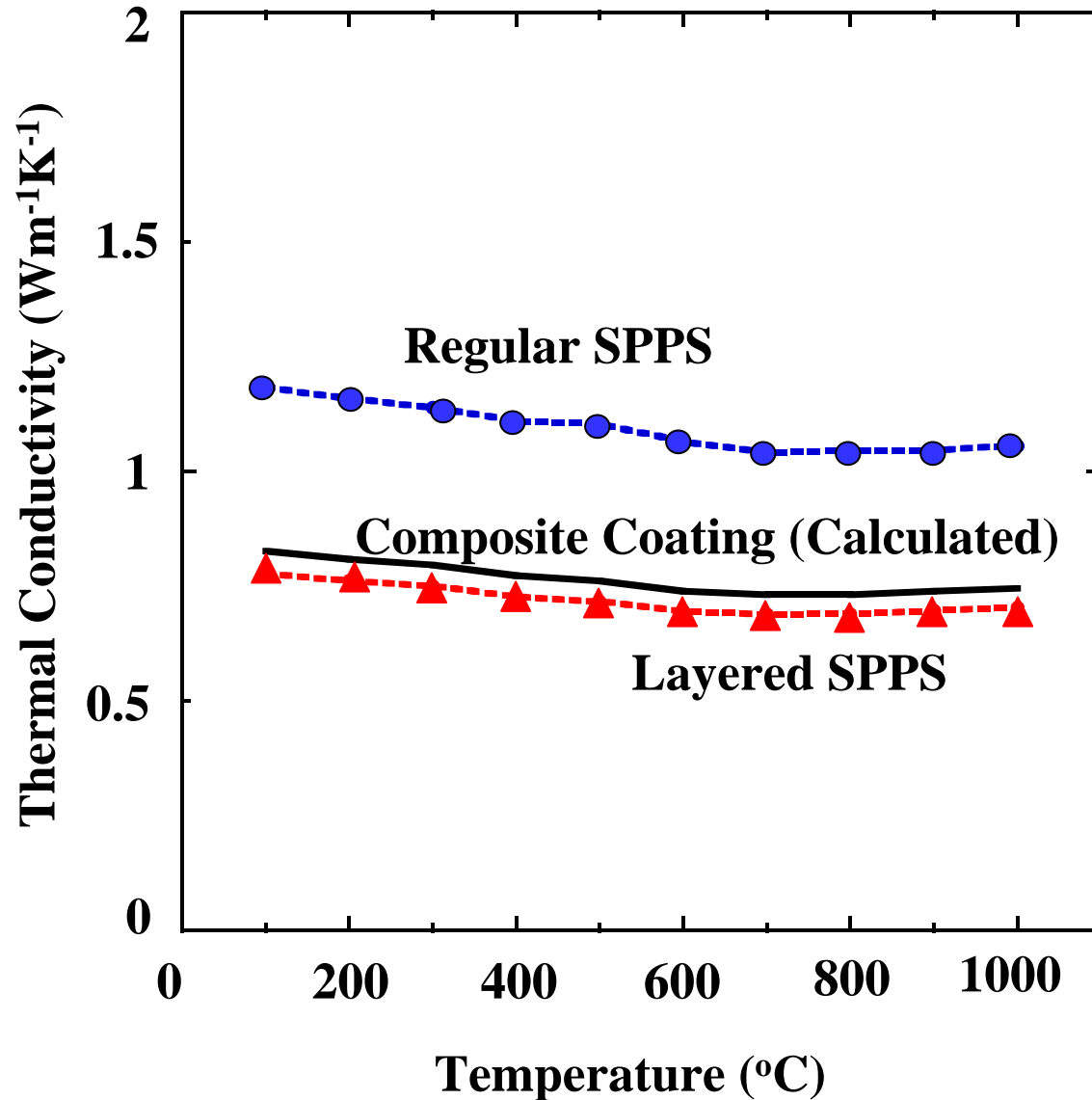


- Calculated Th. Cond. within 10% of Expt.
- Better Than Analytical Model

Low Thermal Conductivity, Improved Durability: SPPS TBCs with Layered Architecture



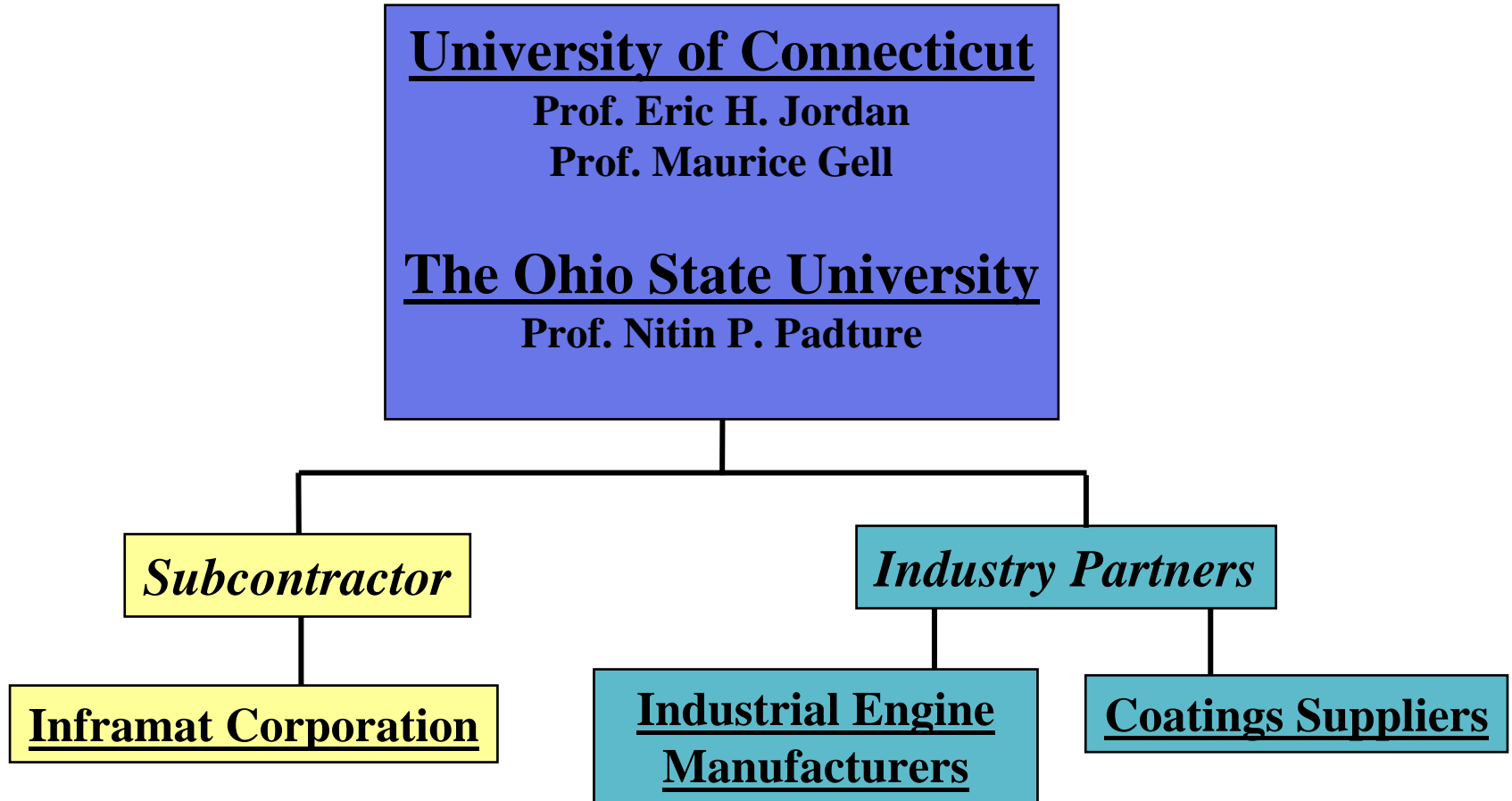
Low Thermal Conductivity, Improved Durability: SPPS TBCs with Layered Architecture



Summary

- **Demonstrated Feasibility of Depositing Ultra-Thick (~3 mm) TBCs Using the SPPS Process**
- **Demonstrated High Durability in Ultra-Thick TBCs**
- **Demonstrated Feasibility of Depositing Layered TBCs with Low Thermal Conductivities**
- **Modeled Effect of Microstructure on Th. Cond.**
- **Demonstrated Feasibility of Depositing SPPS TBCs with Layered Architecture for Low Th. Cond. and High Durability**

Teaming Arrangements



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- **SCIENS/DoE**

